



RECOMMENDED PCB LAYOUT
TOP VIEW ; TOL. ±0.05

DATE CODE

SCHMATIC

- SPECIFICATIONS:**
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
 - CONTACT RESISTANCE: 50mΩ MAX(INITIAL).
 - INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT, IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST: 5,000 CYCLES MIN.
 - INSERTION FORCE: 0.3 - 3kg.
 - WITHDRAWAL FORCE: 0.3 - 3kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
 - MARKING: MARK "Ⓢ" ON TOP OF CONNECTOR.
 - PACKING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
 - HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:

J	WYLAR	1	0.06t	BLACK
I	SHELL	1	BRASS 0.2t	N: 60u" Min.
H	SEPARATOR	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA: GOLD FLASH ON SOLDER AREA: ALL OVER 50u" Min.
F	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	ALL OVER 50u" Min.
E	TIP SPRING	1	PHOSPHOR BRONZE 0.2t	GOLD FLASH ON CONTACT AREA: GOLD FLASH ON SOLDER AREA: Male Solder* ON SOLDER AREA: ALL OVER 50u" Min.
D	RING A	1	PHOSPHOR BRONZE 0.2t	ALL OVER 50u" Min.
C	RING B	1	PHOSPHOR BRONZE 0.2t	
B	EARTH	1	PHOSPHOR BRONZE 0.2t	
A	BODY	1	PA10T, UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
UNLESS OTHERWISE SPECIFIED TOLERANCES				
Singatron Enterprise Co., Ltd. 信登企業股份有限公司				
TITLE: 3.5Ø PHONE JACK				
DWN	Dengfeng	PART NO.	2SJ3095-011111F	
CHKD	BRUCE	SCALE	4:1	UNIT: mm
APVD	LUSSFN	SIZE: A3	SHEET: 1 OF 1	REV: A
CUSTOMER COPY				